

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT						
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT						
<b>CONVEYING PARTY DATA</b>							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jae-Boum PARK</td> <td>06/27/2008</td> </tr> <tr> <td>Seok-Cheol YOON</td> <td>06/27/2008</td> </tr> </tbody> </table>		Name	Execution Date	Jae-Boum PARK	06/27/2008	Seok-Cheol YOON	06/27/2008
Name	Execution Date						
Jae-Boum PARK	06/27/2008						
Seok-Cheol YOON	06/27/2008						
<b>RECEIVING PARTY DATA</b>							
<b>Name:</b>	HYNIX SEMICONDUCTOR, INC.						
<b>Street Address:</b>	San 136-1, Ami-ri, Bubal-eub, Ichon-shi						
<b>City:</b>	Kyoungki-do						
<b>State/Country:</b>	REPUBLIC OF KOREA						
<b>Postal Code:</b>	467-860						
<b>PROPERTY NUMBERS Total: 1</b>							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td><b>Application Number:</b></td> <td>12165118</td> </tr> </tbody> </table>		Property Type	Number	<b>Application Number:</b>	12165118		
Property Type	Number						
<b>Application Number:</b>	12165118						
<b>CORRESPONDENCE DATA</b>							
<b>Fax Number:</b>	(202)408-0924						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
<b>Phone:</b>	202-371-8976						
<b>Email:</b>	firm@rabinberdo.com						
<b>Correspondent Name:</b>	Rabin & Berdo, P.C.						
<b>Address Line 1:</b>	1101 14th St. N.W.						
<b>Address Line 2:</b>	Suite 500						
<b>Address Line 4:</b>	Washington, DISTRICT OF COLUMBIA 20005						
<b>ATTORNEY DOCKET NUMBER:</b>	SHIN-221						
<b>NAME OF SUBMITTER:</b>	Steven M. Rabin - Reg. 29,102						
<b>Total Attachments: 2</b> source=SHIN221-Ass#page1.tif source=SHIN221-Ass#page2.tif							

OP \$40.00 12165118

**ASSIGNMENT OF APPLICATION FOR UNITED STATES LETTERS PATENT**

WHEREAS PARK, Jae-Boum and YOON, Seok-Cheol  
hereinafter referred to collectively as the assignor, has invented a certain improvement relating to SEMICONDUCTOR MEMORY DEVICE

[X] the inventor(s) declaration for said application being executed concurrently with the execution of this instrument; said application to be filed in the United States Patent and Trademark Office;  
[X] said application having been filed in the United States Patent and Trademark Office on June 30, 2008, authorization being hereby given to my attorneys, Steven M. Rabin, Robert H. Berdo, Jr., Phillip G. Avruch, and Allen Wood of RABIN & BERDO, P.C., 1101 14th Street, N.W., Washington, D.C. 20005, to insert here in parentheses (Application Serial No. 12/165,118) the application serial number of said application when known;

AND WHEREAS Hynix Semiconductor, Inc. of San 136-1, Ami-ri, Bubal-eub, Ichon-shi, Kyoungki-do 467-860, Republic of Korea, hereinafter referred to as the assignee, is desirous of acquiring the entire right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof;

NOW THIS WITNESSETH, that for and in consideration of One Dollar (\$1.00), and other good and valuable consideration paid by said assignee to said assignor, the receipt of which is hereby acknowledged, said assignor hereby assigns, sells and transfers to said assignee, and said assignee's successors and assigns, the full and exclusive right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof; said assignee, and said assignee's successors and assigns, to have, hold, exercise and enjoy the said application, including any and all divisions and continuations thereof, and the said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges and advantages in anywise arising from or appertaining thereto, for and during the term or terms of any and all such patents when granted, including any and all renewals, reissues and prolongations thereof, for the use and benefit of said assignee, and said assignee's successors and assigns, in as ample and beneficial a manner as the said assignor might or could have held and enjoyed the same, if this assignment had not been made.

AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and said assignee's successors and assigns, in accordance herewith.

EXECUTED, this 27 day of June, 2008.

**WITNESSES:**

Signature: [Signature]  
Name: HWANG, Ji-yeon  
Address: Seoul

**ASSIGNOR:**

Signature: [Signature]  
Name: PARK, Jae-Boum

Signature: \_\_\_\_\_  
Name: \_\_\_\_\_  
Address: \_\_\_\_\_

RABIN & BERDO, P.C., Washington, D.C.

ASSIGNMENT OF APPLICATION FOR UNITED STATES LETTERS PATENT

Page 2 of 2

**WITNESSES:**

Signature: [Signature]  
Name: HWANG, JT-Yeon  
Address: Seoul

**ASSIGNOR:**

Signature: [Signature]  
Name: YOON, Seok-Cheol

Signature: \_\_\_\_\_  
Name: \_\_\_\_\_  
Address: \_\_\_\_\_

**WITNESSES:**

Signature: \_\_\_\_\_  
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RABIN & BERDO, P.C., Washington, D.C.